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General Description

The MAX172 is a complete 12-Bit analog-to-digital converter (ADC) that combines high speed, low power consumption, and an on-chip voltage reference. The conversion time is 10μ s. The buried zener reference provides low drift and low noise performance.

External component requirements are limited to only decoupling capacitors for the power supply and reference voltages. On-chip clock circuitry is also included which can either be driven from an external source, or in stand-alone applications, can be used with a crystal.

The MAX172 uses a standard microprocessor interface architecture. Three-state data outputs are controlled by Read (RD) and Chip Select (CS) inputs. Data access and bus release times of 90 and 75ns respectively ensure compatibility with most popular microprocessors without resorting to wait states.

Applications

Digital Signal Processing (DSP)

High Accuracy Process Control

High Speed Data Acquisition

Electro-Mechanical Systems

Functional Diagram

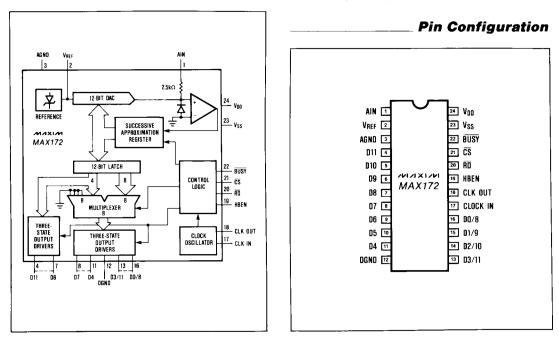
Features

- 12-Bit Resolution and Linearity
- ♦ 10µs Conversion Time
- No Missing Codes
- On-Chip Voltage Reference
- 90ns Access Time
- 215mW Max Power Consumption
- ♦ 24-Lead Narrow DIP Package
- Pin-for-Pin AD7572 Replacement

Ordering Information

PART	TEMP RANGE	PIN- PACKAGE	ERROR (LSB)	PKG CODE
MAX172ACNG	0°C to +70°C	24 Plastic DIP	±0.5	N24-3
MAX172BCNG	0°C to +70°C	24 Plastic DIP	±1	N24-3
MAX172ACWG	0°C to +70°C	24 Wide SO	±0.5	W24-1
MAX172BCWG	0°C to +70°C	24 Wide SO	±1	W24-1
MAX172CC/D	0°C to +70°C	Dice*	±1	—
MAX172AENG	-40°C to +85°C	24 Plastic DIP	±0.5	N24-3
MAX172BENG	-40°C to +85°C	24 Plastic DIP	±1	N24-3
MAX172AMRG	-55°C to +125°C	24 CERDIP	±0.5	R24-4
MAX172BMRG	-55°C to +125°C	24 CERDIP	±1	R24-4

* Consult factory for dice specifications



M/X/M

Maxim Integrated Products

1

For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

Complete 10µs CMOS 12-Bit ADC

ABSOLUTE MAXIMUM RATINGS

V _{DD} to DGND	7V Op
AGND to DGND	.3V I
AIN to AGND	
(Pins 17, 19-21) Digital Output Voltage to DGND0.3V, V _{DD} + 0	Po 3V I
(pins 4-11, 13-16, 18, 22)	Le

perating Temperature Ranges
MAX172XC 0°C to +70°C
MAX172XE
MAX172XM
storage Temperature Range65°C to +160°C
Power Dissipation (any Package) to +75°C 1000mW
Derates Above +75°C by 10mW/°C
ead Temperature (Soldering 10 seconds) +300°C

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS (V_{DD} = +5V ± 5%, V_{SS} = -12V or -15V ± 5%; Slow Memory Mode; T_A = T_{MIN} to T_{MAX} unless otherwise noted, f_{CLK} = 1.25MHz.)

22A 22AC/AE 22AM 22B 22B 22B 22A	$T_A = 25^{\circ}C$ tic Over Temp. $T_A = 25^{\circ}C$ $T_A = T_{MIN}$ to T_{MAX}	12		+ 1/2 + 1/2 + 3/4	Bits	
2AC/AE 2AM 2B nteed Monoton 2B 2A	ic Over Temp. T₄ = 25°C	12		± 1/2 ± 3/4	<u>+</u>	
2AC/AE 2AM 2B nteed Monoton 2B 2A	ic Over Temp. T₄ = 25°C		······································	± 1/2 ± 3/4	LSB	
22AM 22B 1teed Monoton 22B 22A	ic Over Temp. T₄ = 25°C			+3/4	LSB	
2B 2A	T₄ = 25° C			±1		
2A				+1	LSB	
	A MIN ** MAX			±4 ±6	LSB	
	$T_A = 25^{\circ}C$ $T_A = T_{MIN}$ to T_{MAX}			±3 ±4		
'2B	T _A = 25°C			+ 15		
'2A	T _A = 25°C			+ 10	LSB	
	· · · · ·			+ 45	ppm/°(
		0		5	V	
0V to +5V			3.5	rnA		
5°C		-5.2	-5.25	-5.3	V	
		40		ppm/°		
6)				500	μA	
		-				
D, HBEN, CLK	IN			0.8	V	
D, HBEN, CLK	IN	2.4			V	
CS, RD, HBEN, CLKIN				10	pF	
D, HBEN	VIN = 0 to V _{DD}			+ 10 + 20	μA	
D11-D0/8, BUSY, CLKOUT I _{SINK} = 1.6mA				0.4	V	
D11-D0/8, BUSY, CLKOUT ISOURCE = 200µA					V	
D11-D0/8, V_{OUT} = 0V to V_{DD}				+ 10	μA	
				15	pF	
Y	10/8, V _{OUT} = 0V	10/8, V _{OUT} = 0V to V _{DD}	10/8, V _{OUT} = 0V to V _{DD}	10/8, V _{OUT} = 0V to V _{DD}		

MAX172

Complete 10µs CMOS 12-Bit ADC

ELECTRICAL CHARACTERISTICS (Continued) $(V_{DD} = +5V \pm 5\%, V_{SS} = -12V \text{ or } -15V \pm 5\%$; Slow Memory Mode; $T_A = T_{MIN}$ to T_{MAX} unless otherwise noted, $f_{CLK} = 1.25MHz$.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
CONVERSION TIME						
MAX172	t _{CONV}	Synchronous (12.5 clock cycles) Asynchronous (12 to 13 clock cycles)			10 10.4	μs
POWER SUPPLY REJECT	ION					
V _{DD} Only		FS Change, V_{SS} = -15V, V_{DD} = 4.75V to 5.25V		±1/2		LSB
V _{SS} Only		FS Change, V_{DD} = 5V, V_{SS} = -5% to +5%		LSB		
POWER REQUIREMENTS	,,,					
V _{DD}		±5% for Specified Performance		5		V V
V _{SS} (Note 8)		±5% for Specified Performance		-12 or -1	5	V
		$\overline{CS} = \overline{RD} = V_{DD}$, AIN = 5V		5	7	mA
I _{SS}		$\overline{CS} = \overline{RD} = V_{DD}$, AIN = 5V		8	12	mA
Power Dissipation		V _{DD} = +5V, V _{SS} = -15V		145	215	mW

MAX172

Note 1: Typical change over temp is +1 LSB. Note 2: $V_{DD} = +5V$, $V_{SS} = -15V$, FS = +5.000V, Ideal last code transition = FS - 3/2LSB. Note 3: Full Scale TC = Δ FS/ Δ T, where Δ FS is full scale change from T_A = 25°C to T_{MIN} or T_{MAX}.

Note 3: Full scale TC = $\Delta F_{S/\Delta}$, where ΔF_{S} is the scale change from $T_A = 25^{\circ}$ C to T_{MIN} or T_{MAX} Note 4: Includes internal reference drift. Note 5: V_{REF} TC = $\Delta V_{REF}/\Delta T$, where ΔV_{REF} is reference voltage change from $T_A = 25^{\circ}$ C to T_{MIN} or T_{MAX} Note 6: Output current should not change during conversion. Note 7: Guaranteed by design, not subject to test. Note 8: Functional operation at $V_{SS} = -12V + 5\%$ is guaranteed by testing offset error and full scale error.

TIMING CHARACTERISTICS (Note 9)

(V_{DD} = +5V, V_{SS} = -12V or -15V; T_A = T_{MIN} to T_{MAX} unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	T _A = 25°C		MAX172C/E		MAX172M		UNITS	
			MIN	ТҮР	MAX	MIN	MAX	MIN	MAX	
CS to RD Setup Time	t ₁		0			0		0		ns
RD to BUSY Delay	t ₂	C _L = 50pF		90	190		230		270	ns
Data Access Time (Note 10)	t ₃	C _L = 20pF C _L = 100pF		60 70	90 125		110 150		120 170	ns
RD Pulse Width	t ₄		t ₃			t ₃		t ₃		
CS to RD Hold Time	t ₅		0			0		0		ns
Data Setup Time After BUSY Note (10)	t ₆				70		90		100	ns
Bus Relinquish Time (Note 11)	t ₇		20		75	20	85	20	90	ns
HBEN to RD Setup Time	t ₈		0			0		0		ns
HBEN to RD Hold Time	t ₉		0			0		0		ns
Delay Between Read Operations	t ₁₀	_	200			200		200		ns

Timing specifications are sample tested at 25°C to ensure compliance. All input control signals are specified with Note 9: t_r = t_r = 5ns (10% to 90% of +5V) and timed from a voltage level of +1.6V. Note 10: t_3 and t_6 are measured with the load circuits of Figure 1 and defined as the time required for an output to cross

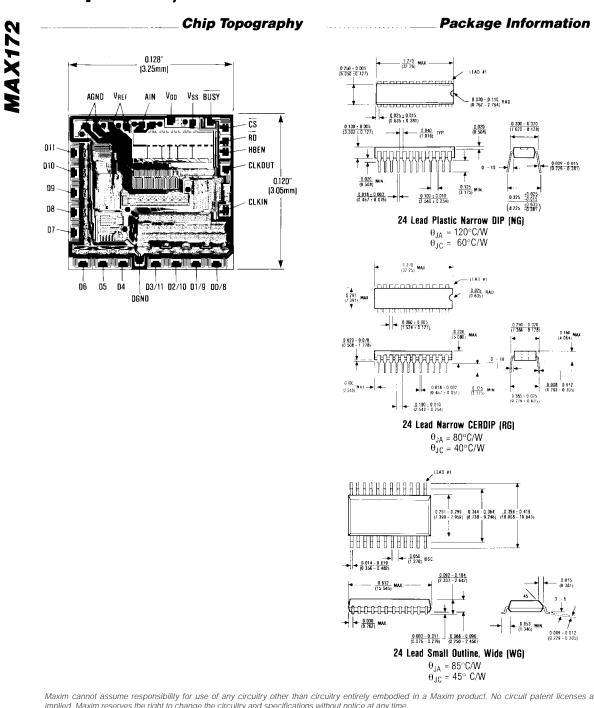
0.8V or 2.4V.

Note 11: t₇ is defined as the time required for the data lines to change 0.5V when loaded with the circuits of Figure 2.

For additional information on using the MAX172 please refer to MAX162 data sheet.

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3



Complete 10µs CMOS 12-Bit ADC

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

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